
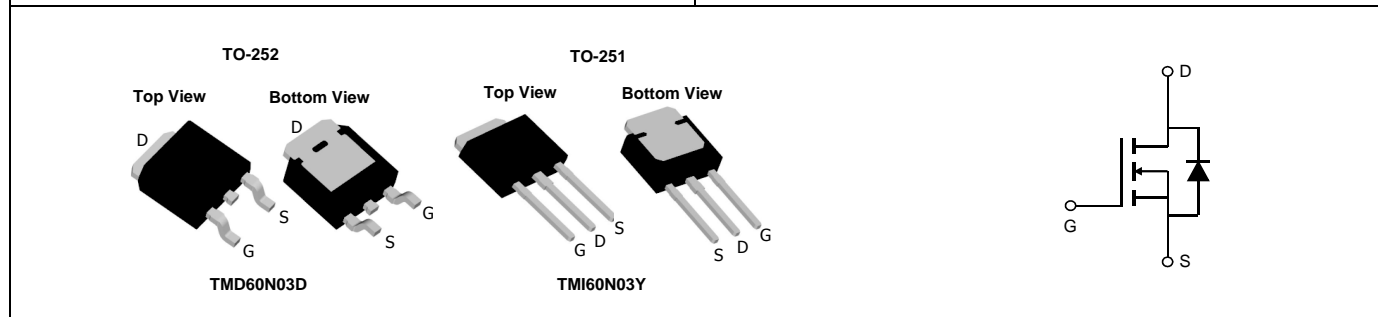


**TMD60N03D / TMI60N03Y
N-CHANNEL ENHANCEMENT MOSFET**

<p>General Description</p> <p>The 60N03 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.</p>	<p>Product Summary</p> <p>$V_{DS}=30V, I_D=60A$</p> <p>$R_{DS(ON)} < 10m\Omega @ V_{GS}=10V$</p> <p>$R_{DS(ON)} < 15m\Omega @ V_{GS}=4.5V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
--	---



Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Maximum	Unit	
VDSS	Drain-to-Source Voltage	30	V	
VGSS	Gate-to-Source Voltage	± 20	V	
I_D	Continuous Drain Current	$T_C=25^\circ C$	60	A
		$T_C=100^\circ C$	37	A
IDM	Pulsed Drain Current	$T_C=25^\circ C$	200	A
PD	Maximum Power Dissipation	$T_C=25^\circ C$	54	W
		$T_C=100^\circ C$	21	
T_J, T_{STG}	Junction & Storage Temperature Range	-55~150	$^\circ C$	

Thermal Characteristics

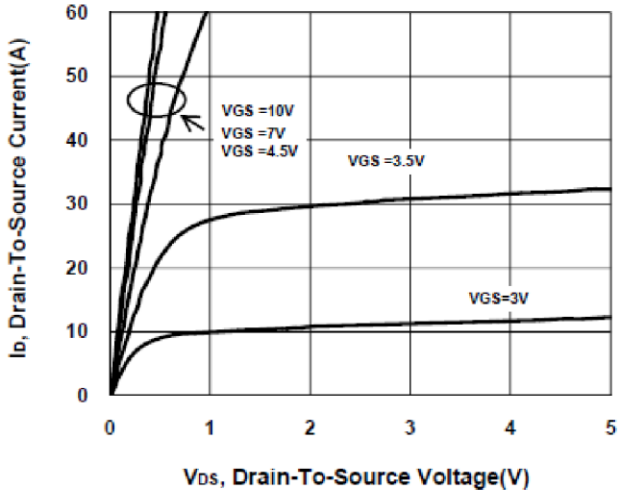
Symbol	Parameter	Typical	Unit
$R_{\theta jc}$	Thermal Resistance-Junction to Case	2.3	/W
$R_{\theta ja}$	Thermal Resistance-Junction to Ambient	62.5	

Electrical Characteristics (TA=25°C unless otherwise noted)

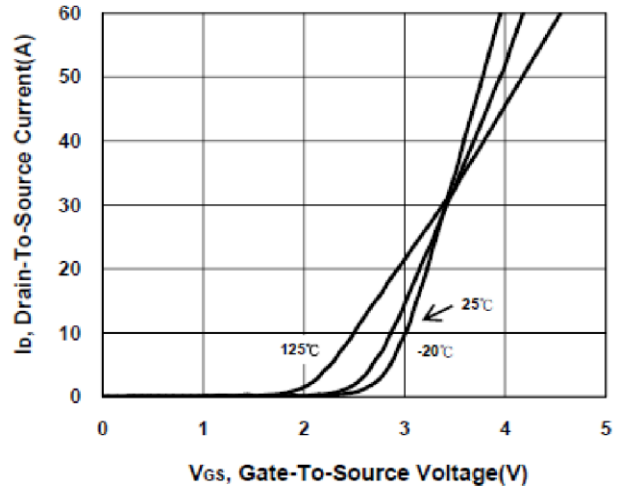
Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	—	—	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	—	—	1	uA
		T _J =85°C	—	—	10	
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	1.7	3	V
IGSS	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	—	—	±100	nA
R _{DS(on)} 1	Drain-Source On-Resistance	V _{GS} =10V, I _D =15A	—	8.5	10	mΩ
		V _{GS} =4.5V, I _D =15A	—	12	15	
Diode Characteristics						
VSD1	Diode Forward Voltage	I _{SD} =15A, V _{GS} =0V	—	0.88	1.3	V
IS	Diode Continuous Forward Current				55	A
trr	Reverse Recovery Time	I _F =15A, dI/dt=100A/us	—	23		ns
Qrr	Reverse Recovery Charge		—	15		nC
Dynamic Characteristics²						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Frequency=1MHz	—	1.5	—	
C _{iss}	Input Capacitance		—	920		pF
C _{oss}	Output Capacitance	V _{GS} =0V, V _{DS} =30V, Frequency=1MHz	—	187		
C _{rss}	Reverse Transfer Capacitance		—	130		
td(on)	Turn-On Delay Time		—	15		ns
t _r	Turn-On Rise Time	V _{DD} =15V, R _L =30 I _D =15A, V _{GS} =10V	—	25		
td(off)	Turn-Off Delay Time	R _G =6	—	60		
t _f	Turn-Off Fall Time		—	17		
Gate Charge Characteristics²						
Q _g	Total Gate Charge		—	22		nC
Q _{gs}	Gate-to-Source Charge	V _{DS} =15V, V _{GS} =10V I _D =15A	—	5		
Q _{gd}	Gate-to-Drain Charge		—	6.5		

Note: 1: Pulse test; pulse width \leq 300ns, duty cycle \leq 2%. 2: Guaranteed by design, not subject to production testing.

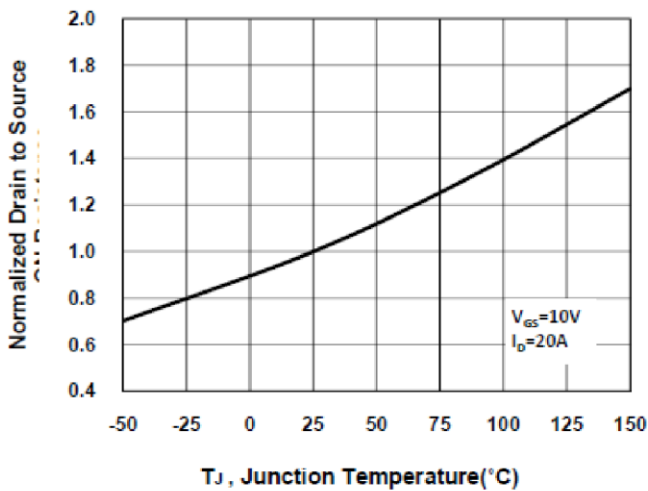
Typical Operating Characteristics
Output Characteristics



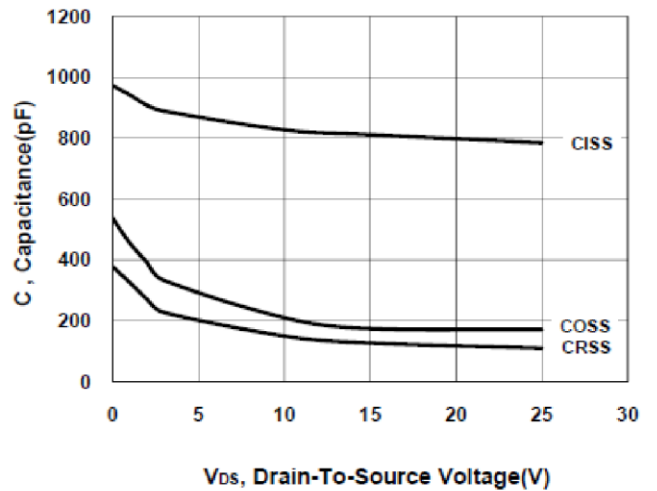
Transfer Characteristics



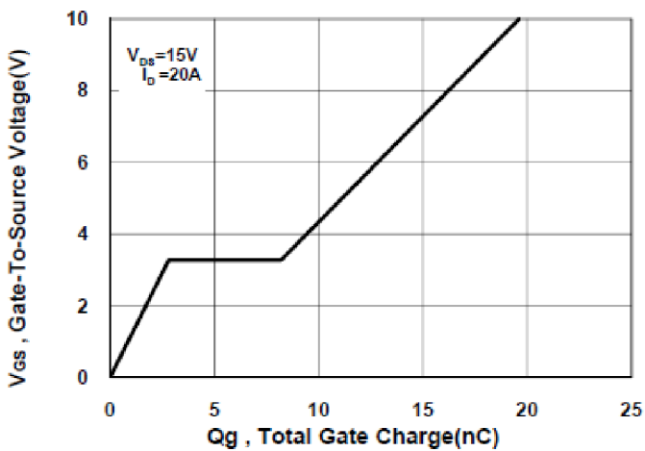
On-Resistance VS Temperature



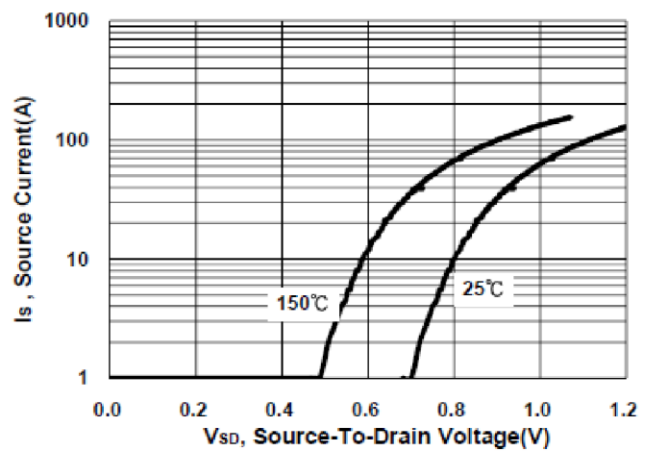
Capacitance Characteristic



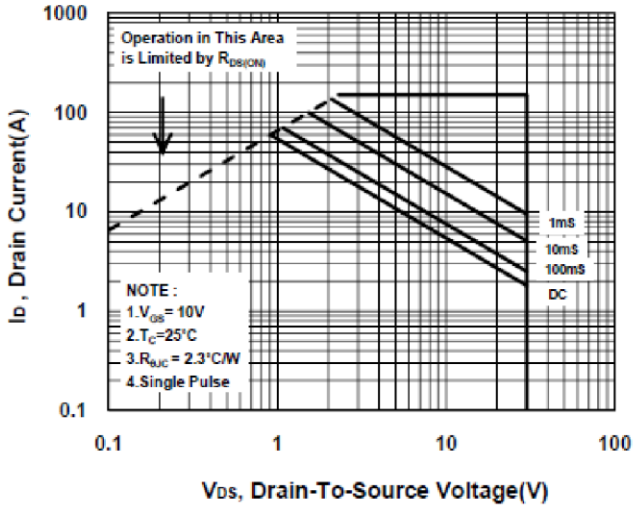
Gate charge Characteristics



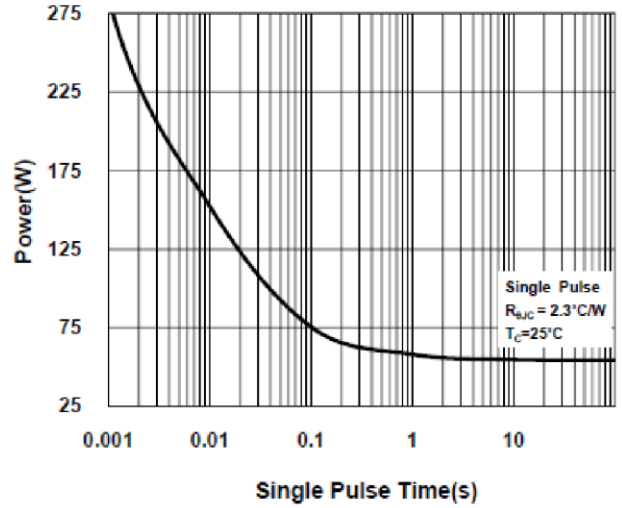
Source-Drain Diode Forward Voltage



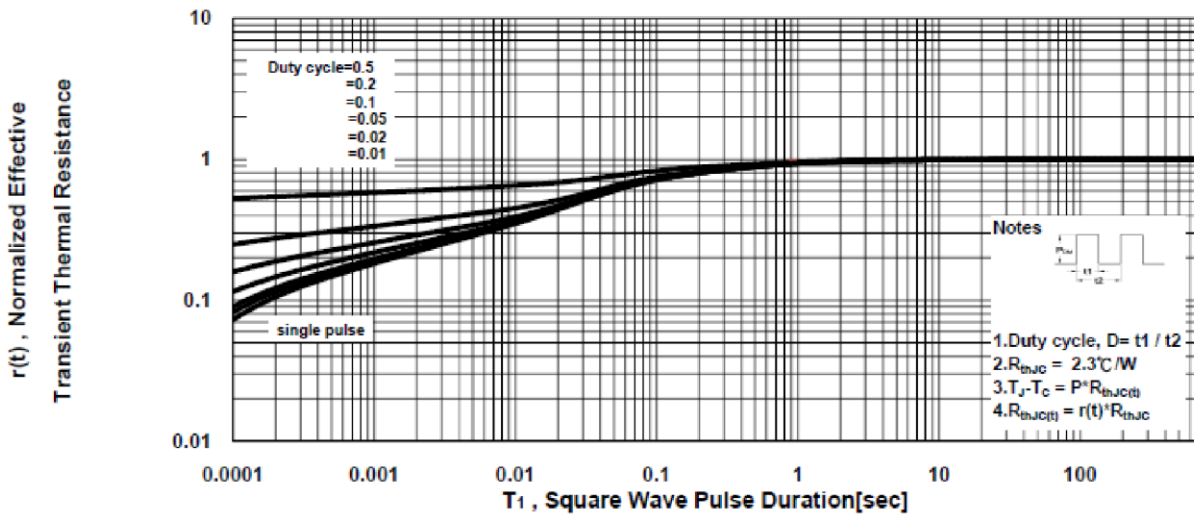
Typical Operating Characteristics Safe Operating Area



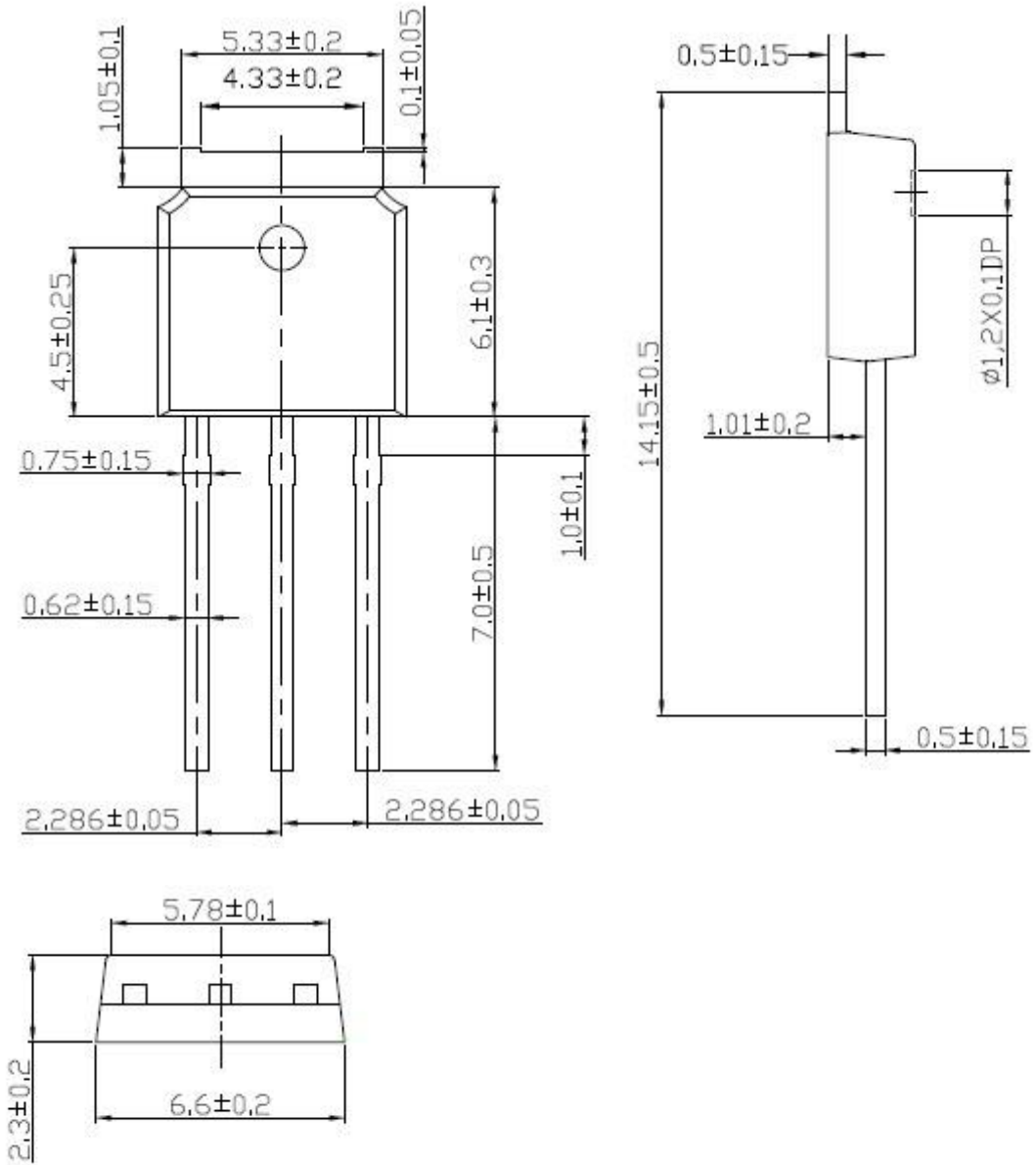
Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

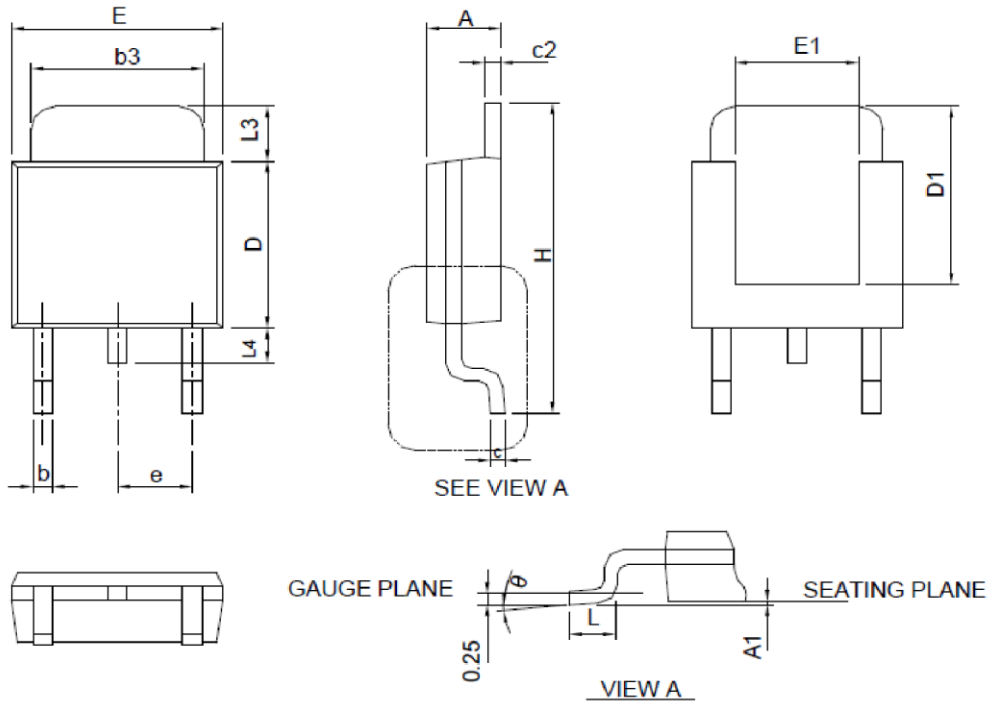


Package Information TO-251



Package Information

TO-252



L O B M S	TO-252-3			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
theta	0°	8°	0°	8°

Note : Follow JEDEC TO-252 .